

Amendments to the Specification:

Please replace paragraph [0002] with the following amended paragraph:

[0002] Low fiber optic transceiver cost is achieved by using injection molded plastic parts whenever possible. In addition to having low material and fabrication ~~cost~~ costs, injection molded plastic parts enable snap-fit assemblies, further decreasing the cost of the transceiver by eliminating fasteners and assembly labor. The disadvantages of injection molded plastic transceiver housings include relatively low mechanical strength and poor EMI performance (since the plastic is electromagnetically transparent, allowing EMI to escape from the transceiver module thru the bezel opening).

Please replace paragraph [0016] with the following amended paragraph:

[0016] Fig. 2 illustrates EMI shield 14 separate from lower housing 12 in one embodiment of the invention. EMI shield 14 includes an electrically conductive mesh 22, electrically conductive shield sidewalls 24 around mesh 22, and electrically conductive contact fingers 26 (not all labeled) extending from shield sidewalls 24. Mesh 22 has small perforations that shield EMI over the frequency range of interest from escaping through a nose 54 (Fig. 3) of fiber optic module 10. Mesh 22 further defines openings 28 for receiving fiber optic connectors from a fiber optic cable. Contact fingers 26 also shield EMI from escaping around fiber optic module 10 when it is mounted to a bezel of a host device. Contact fingers 26 also provide frequent physical contact to the bezel opening thru which the module is inserted. Typically EMI shield 14 is grounded through this physical contact with the bezel of the host device, which is grounded. EMI shield 14 can be stamped or etched from a sheet metal and then folded into its final shape with well known sheet metal fabrication techniques. In one embodiment, the shield sidewalls 24 ensure that the contact fingers 26 are in the correct position (along the long axis of the module) to interface to the bezel opening where they contact chassis ground. In other embodiments, shield sidewalls 24 are not necessary if the bezel happens to be in the same plane as the insert-molded conductive mesh 22 so there is already physical contact between EMI shield 14 and the chassis ground.

Please replace paragraph [0018] with the following amended paragraph:

[0018] Lower housing 12 is injection molded through mesh 22 of EMI shield 14. For example, a mold of lower housing 12 is loaded with EMI shield 14 and a thermoplastic material is injected into the mold. The thermoplastic material flows through the perforations of mesh ~~[[40]]~~ 22 and forms ~~[[in]]~~ a high-strength monolithic lower housing 12. Specifically, housing floor 32,

sidewalls 38 and 40, and fiduciary 48 are injection molded through mesh 22 to be integral with nose 54 while shield sidewalls 24 and contact fingers 26 at least partially surround nose 54.

Please replace paragraph [0019] with the following amended paragraph:

[0019] Fig. 5 illustrates optoelectronic subassembly 60 mounted in lower housing 12 in one embodiment of the invention. Optoelectronic subassembly 60 includes a printed circuit board (PCB) 62, an optical transmitter subassembly 64 (e.g., a light source such as a vertical cavity surface emitting laser) mounted on PCB 62, and a first connector interface (or transmitter port) 66 mounted to transmitter subassembly 64. Optoelectronic subassembly 60 may further include an optical receiver subassembly 68 (e.g., a photo detector such as a photodiode) mounted on PCB 62, and a receiver connector interface (or receiver port) 70 mounted to receiver subassembly 68. Each connector interface includes a circumferential slots slot 72 on ~~their~~ its outer surface that fit fits into U-shaped ~~cutouts~~ cutout 50 (Fig. 3). Once seated in lower housing 12, the ports of connector interface 66 and 70 are aligned with and pass through openings 28 (Fig. 2) of mesh 22 to receive fiber optic connectors from a fiber optic cable. Connector interface 66 and 70 can be any connector form factor, including SC, LC, and MTRJ form factors. When mounted inside lower housing 12, pins 74 (only one is labeled) of PCB 62 ~~pretrudes~~ protrude through pin holes 36 (Fig. 4) for making electrical contact with a host circuit board.

Please replace paragraph [0020] with the following amended paragraph:

[0020] Referring back to Fig. 1, upper housing 16 is snap-fitted onto lower housing 12 to enclose optoelectronic subassembly ~~[[30]]~~ 60. Upper housing 16 includes vents 82 and cantilever hooks 84 (only one is visible).